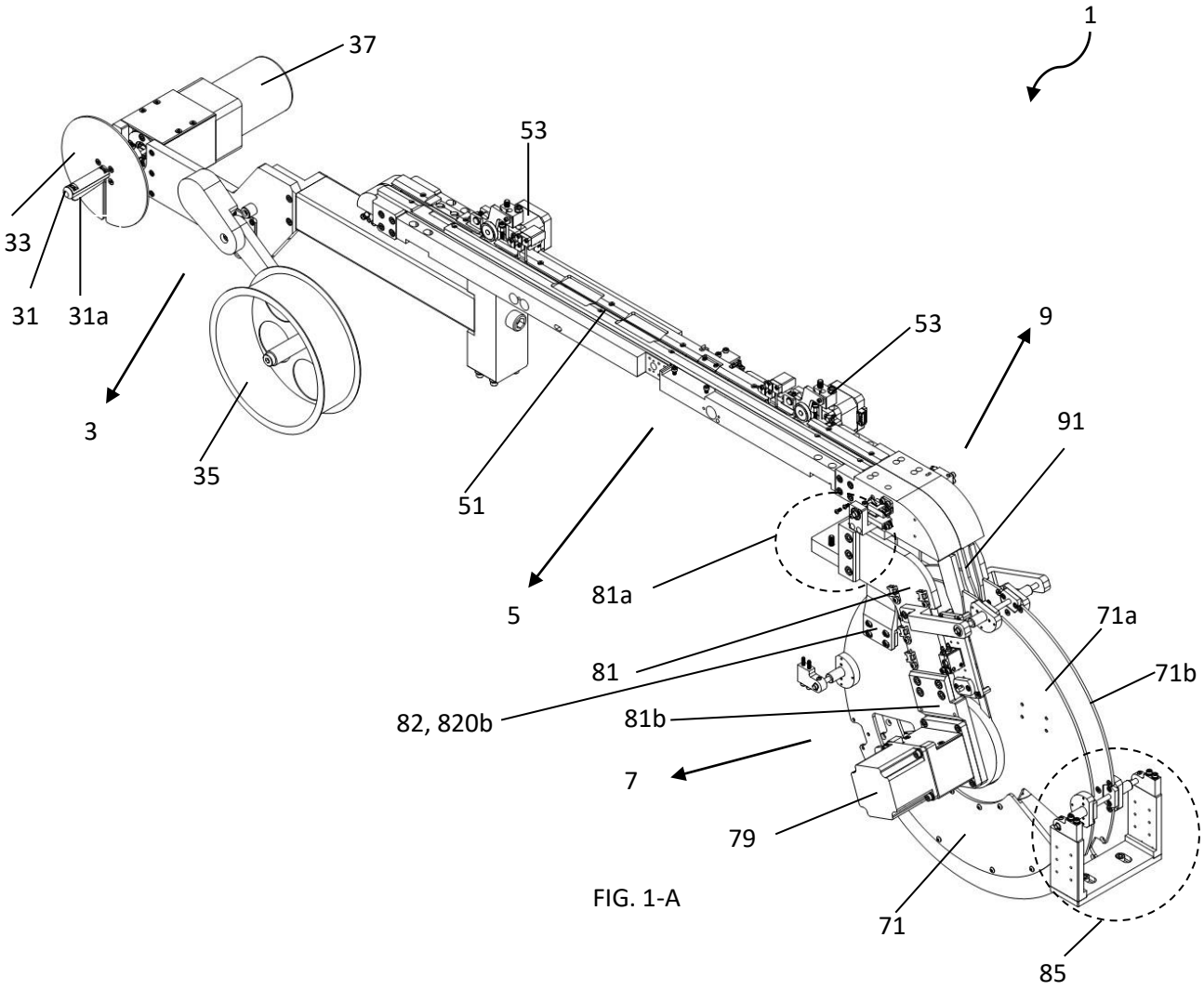

1
37
53
33
31
31a
3
35
51
53
9
91
5
81a
71a
81
71b
82, 820b
81b
7
79
71
85

FIG. 1-A

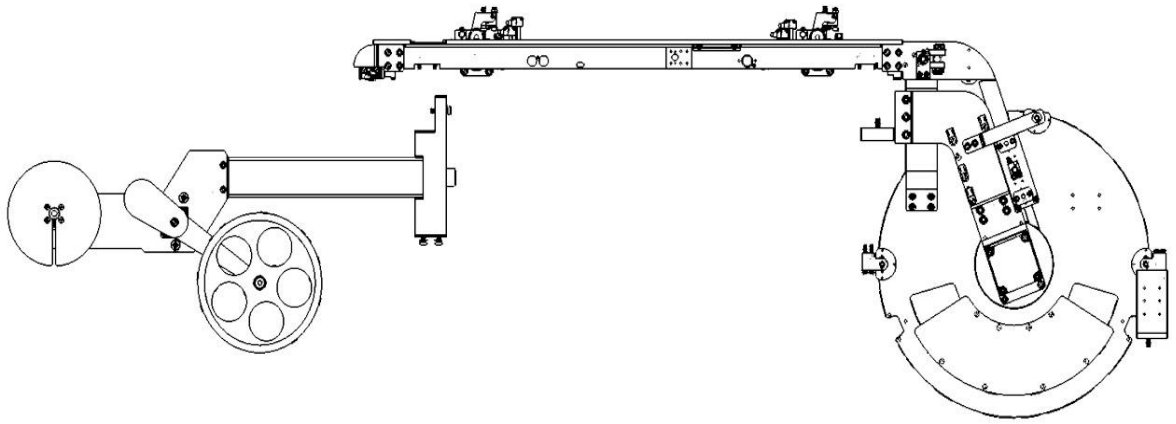


FIG. 1-B

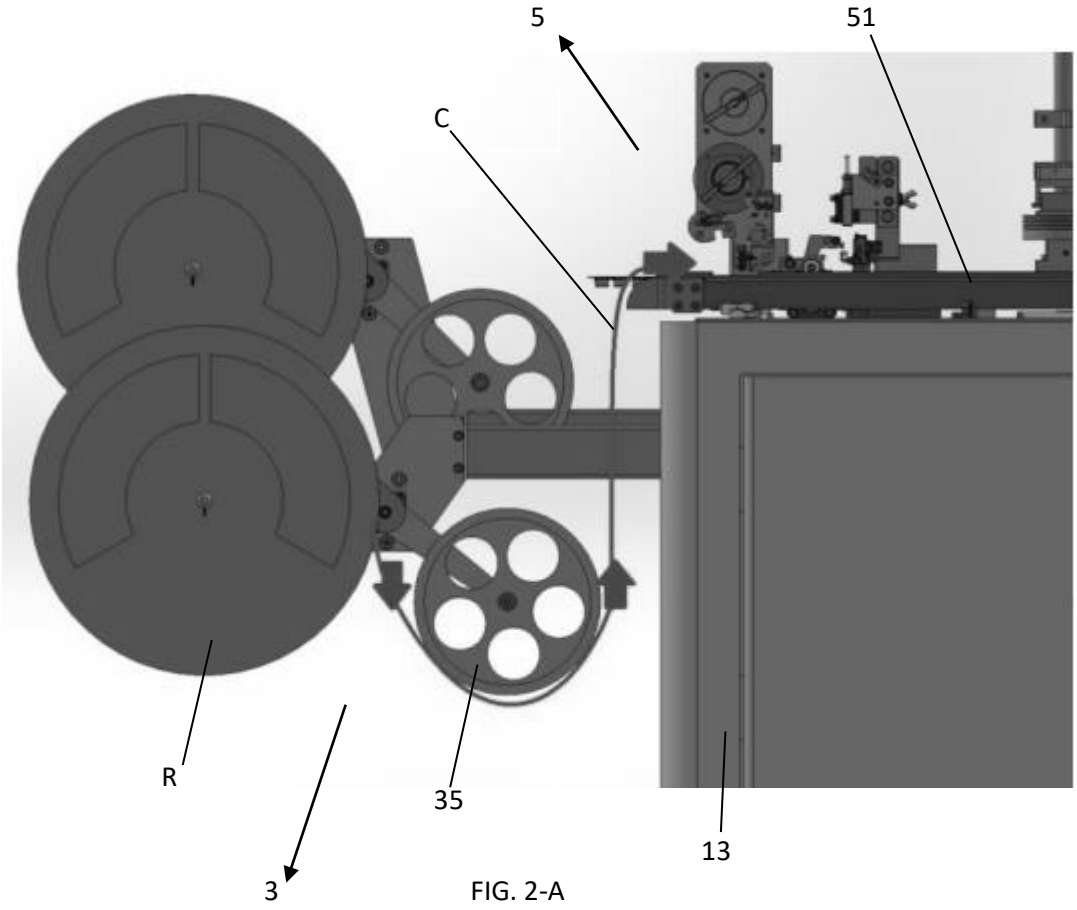


FIG. 2-A

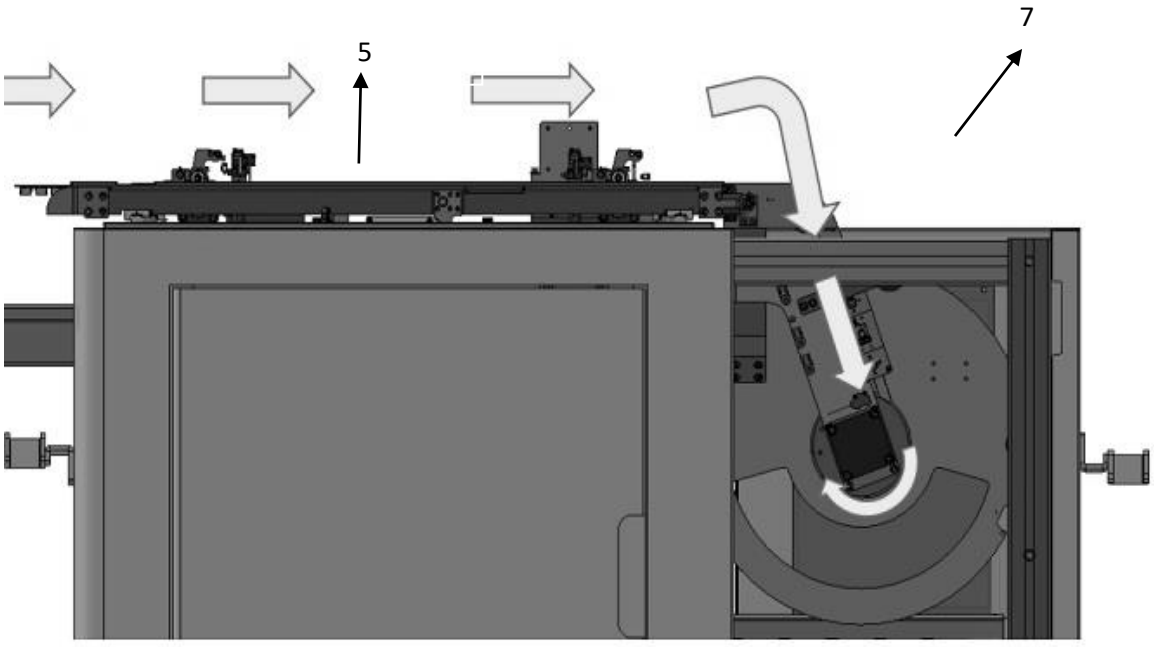


FIG. 2-B

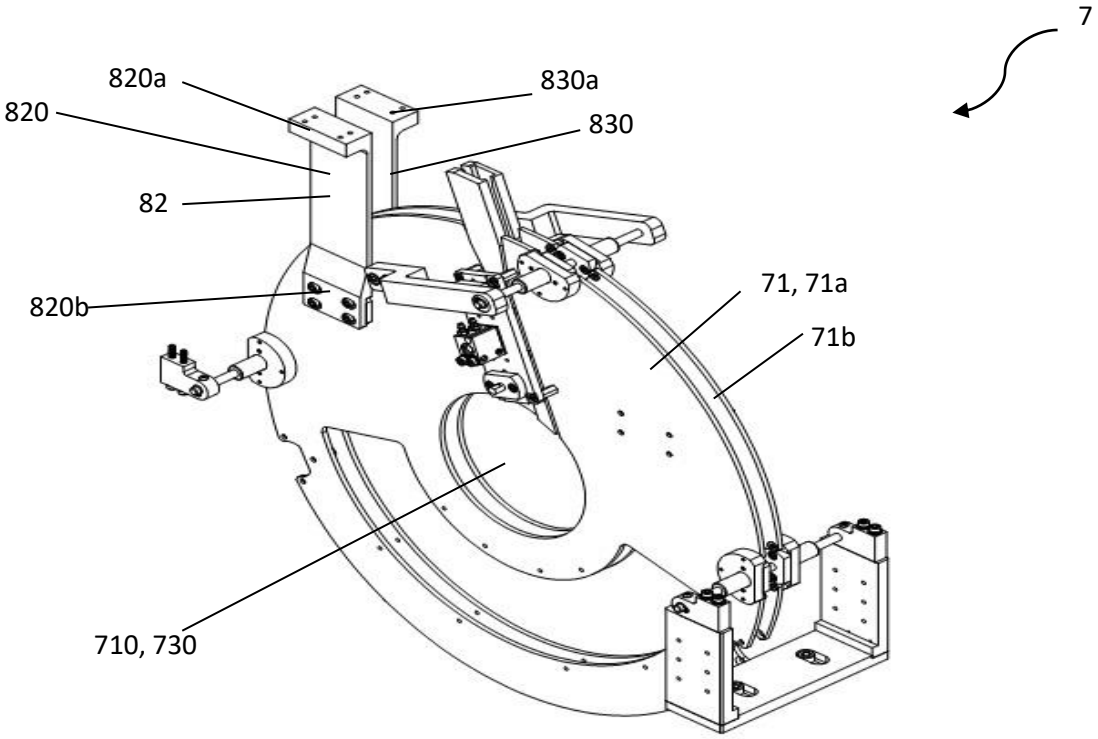


FIG. 3-A

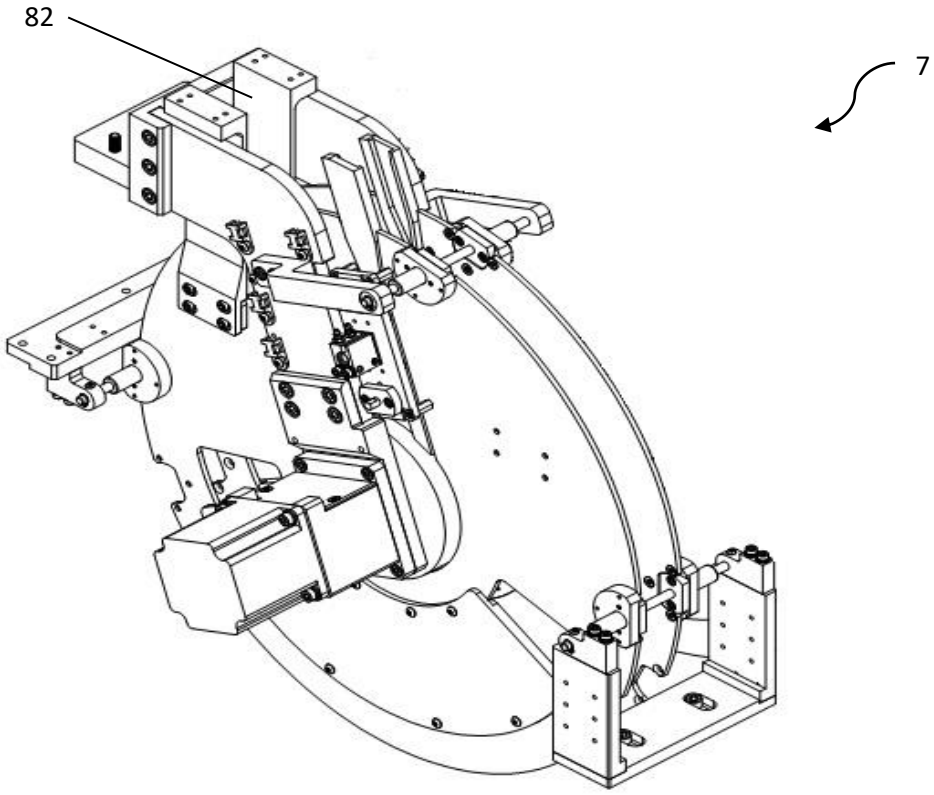


FIG. 3-B

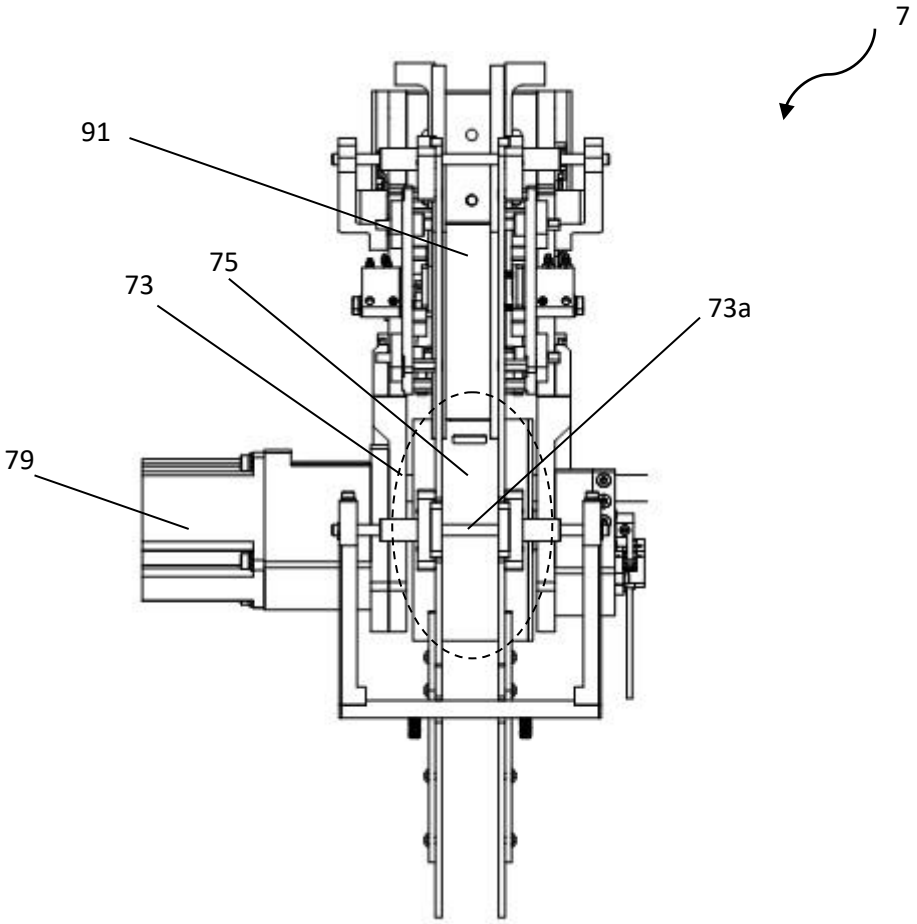


FIG. 3-C

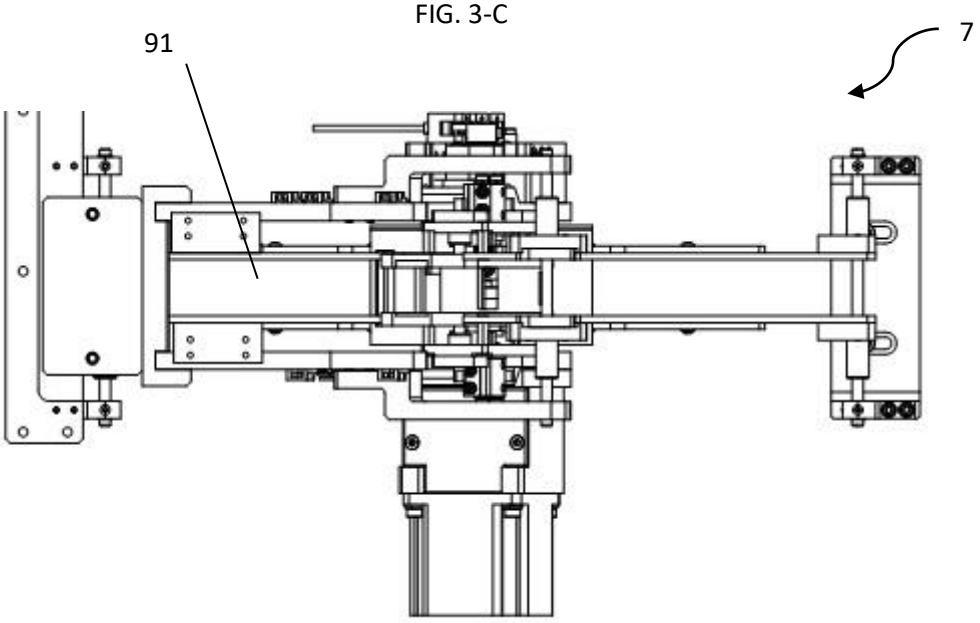


FIG. 3-D

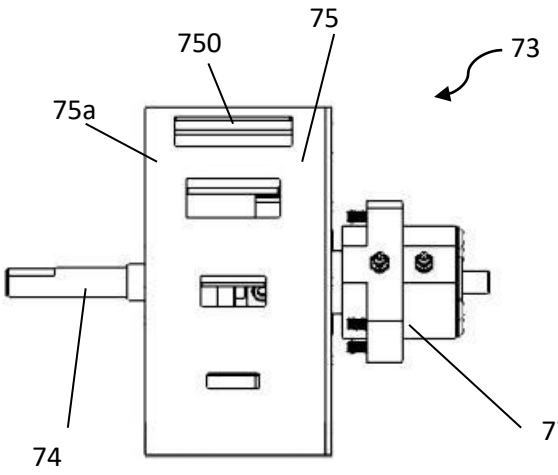


FIG. 4-A

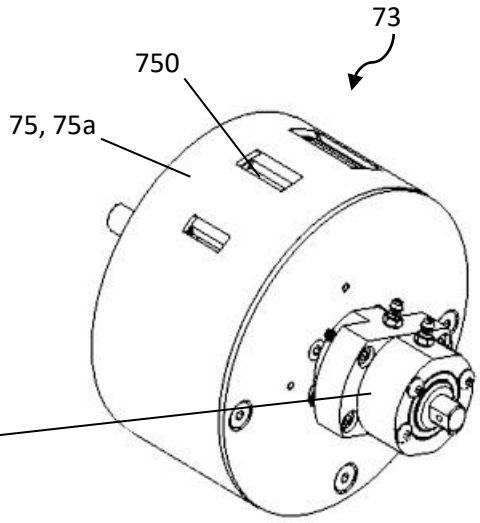


FIG. 4-B

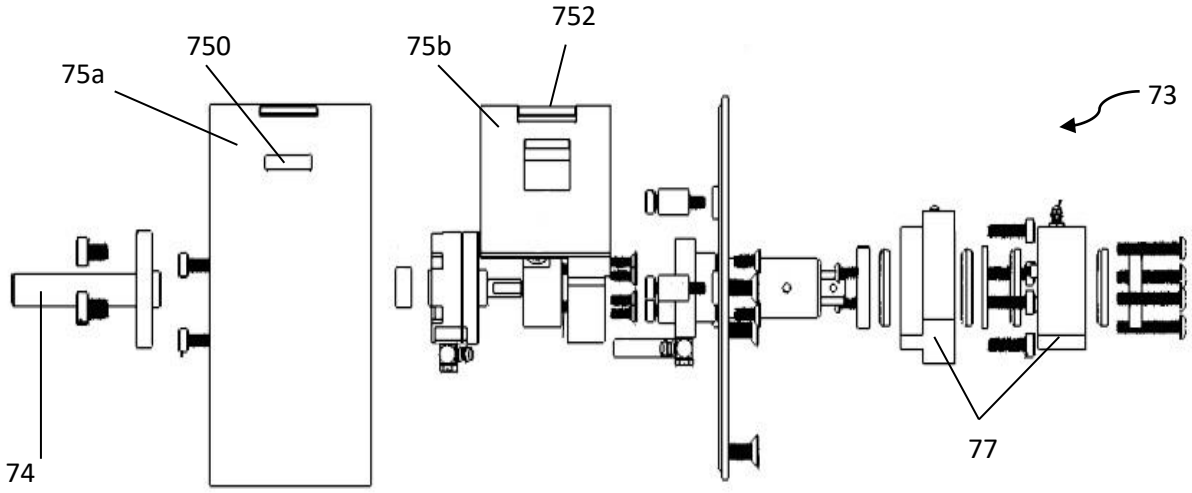


FIG. 4-C

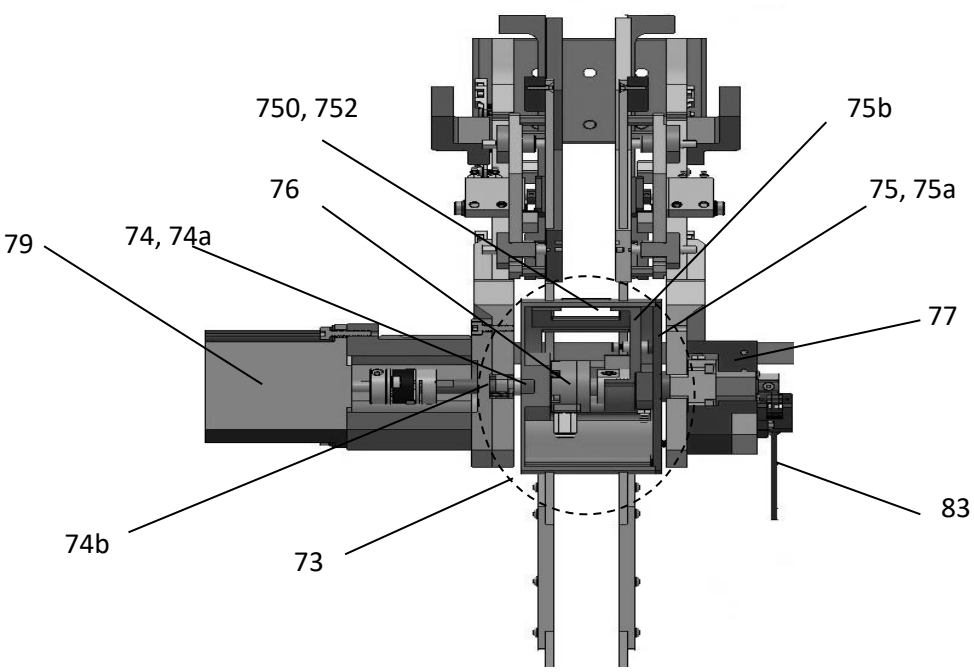


FIG. 4-D

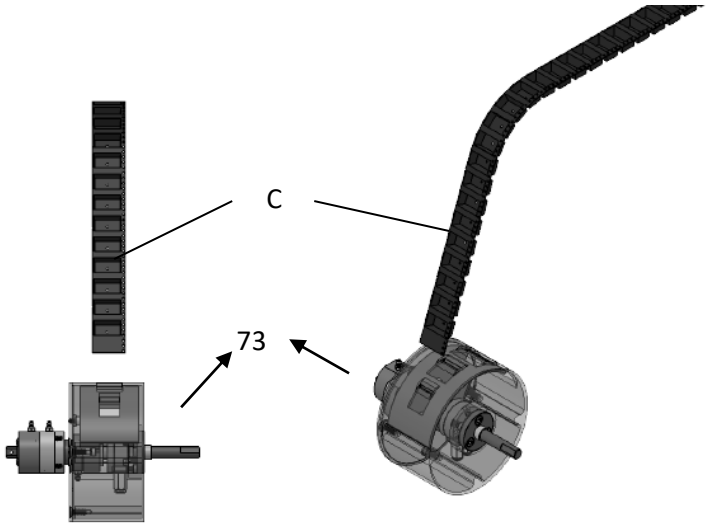


FIG. 5

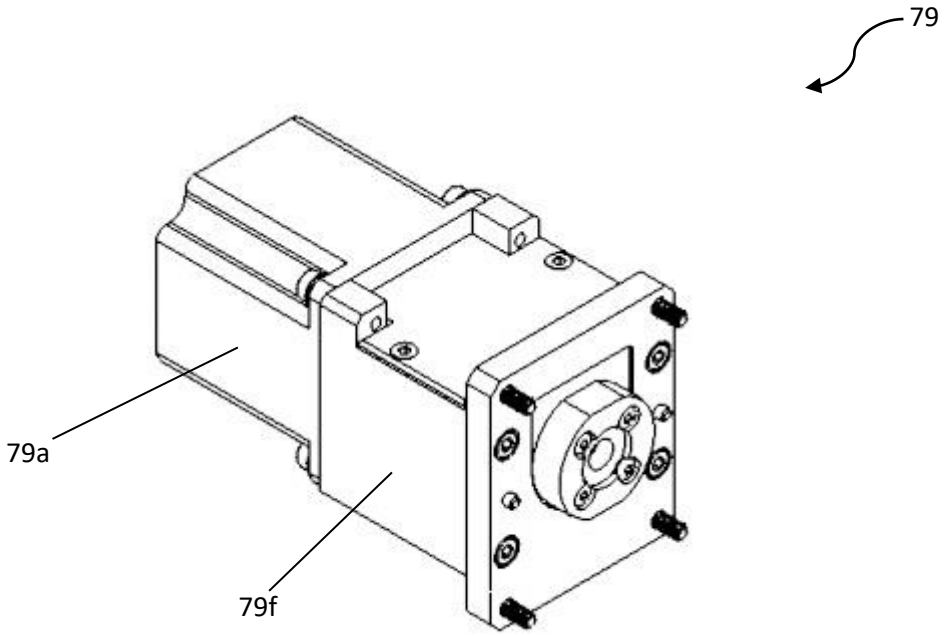


FIG. 6-A

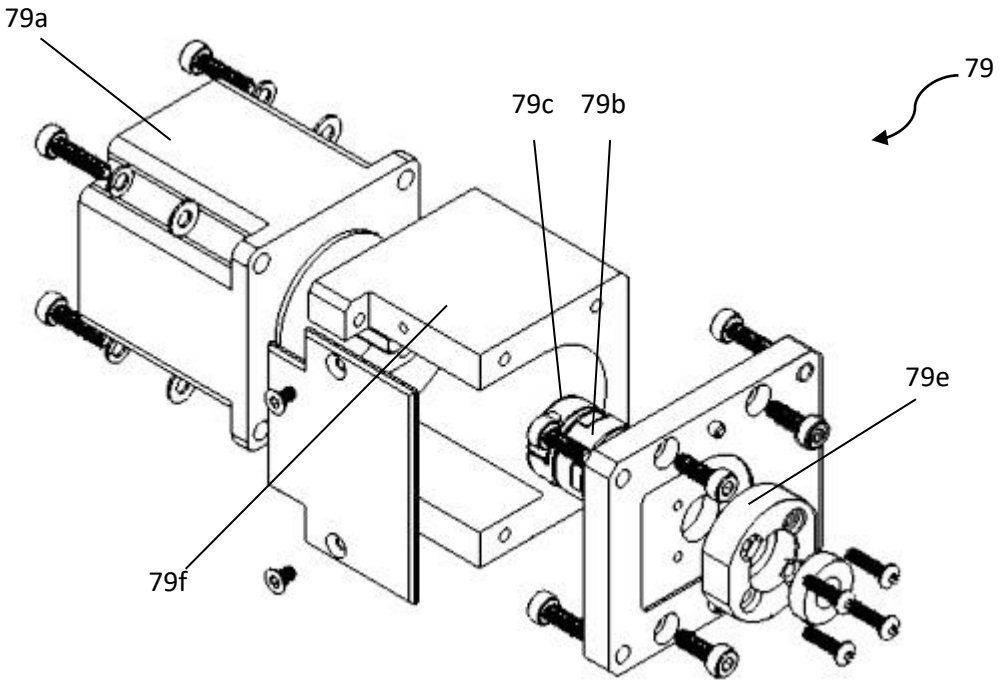


FIG. 6-B

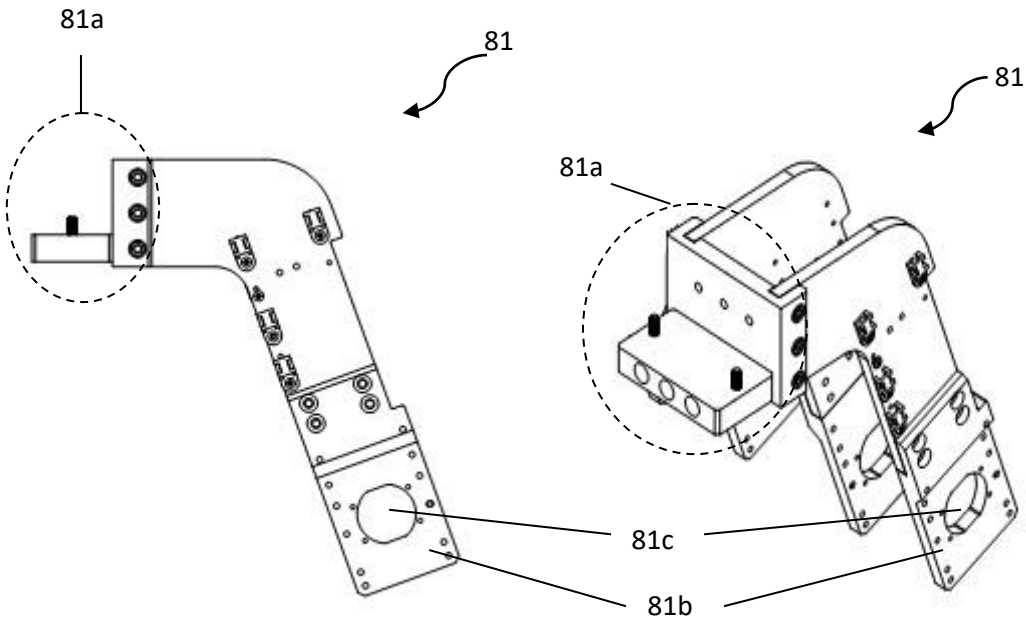


FIG. 7-A

FIG. 7-B

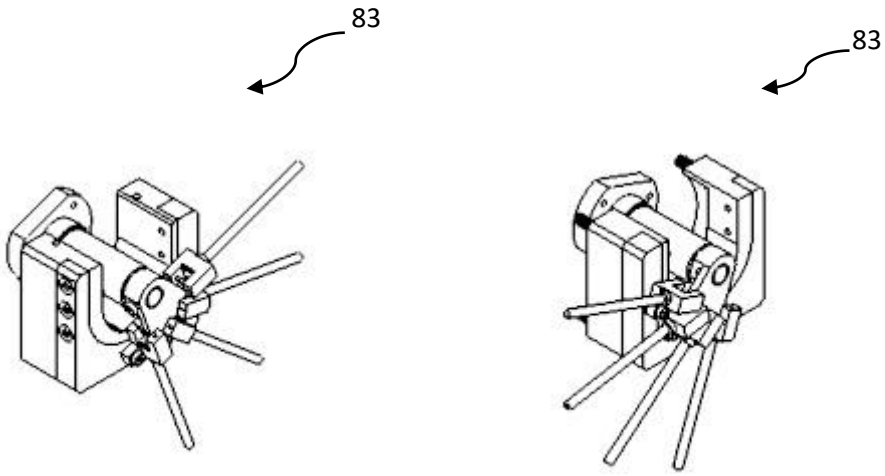


FIG. 8-A

FIG. 8-B

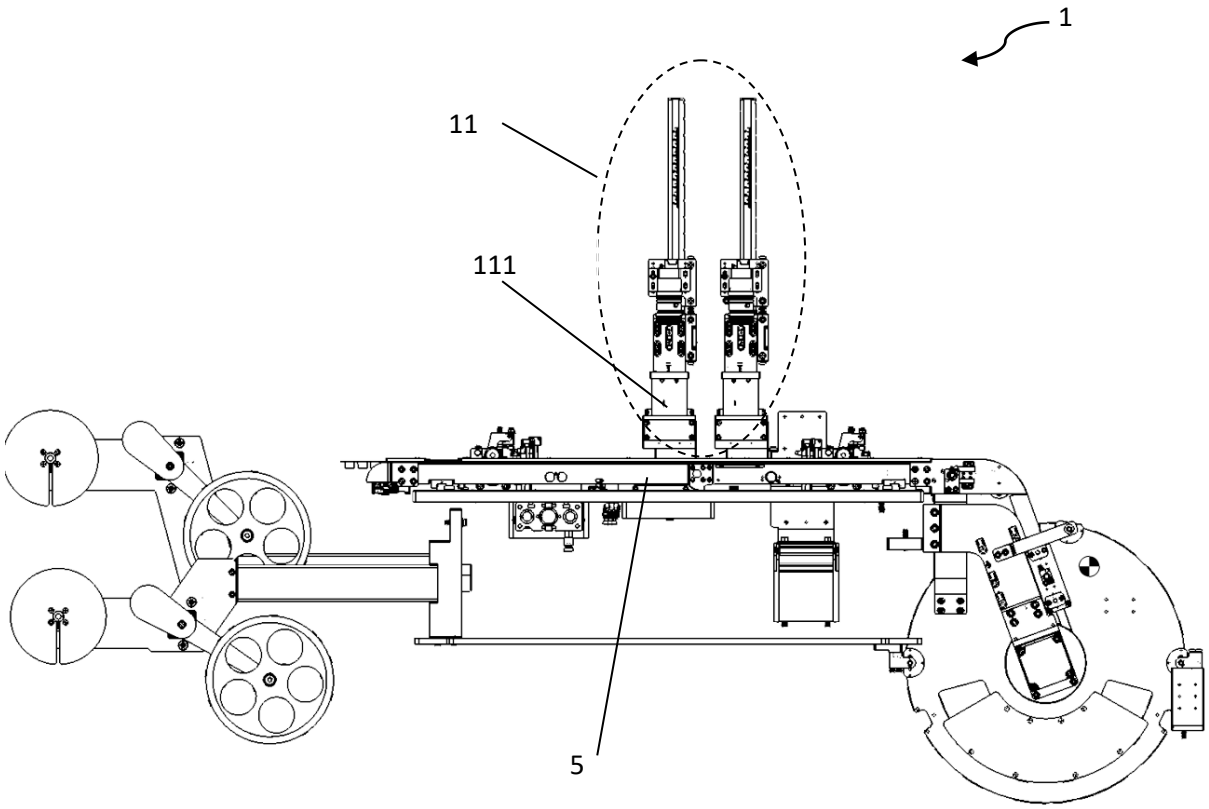


FIG. 9

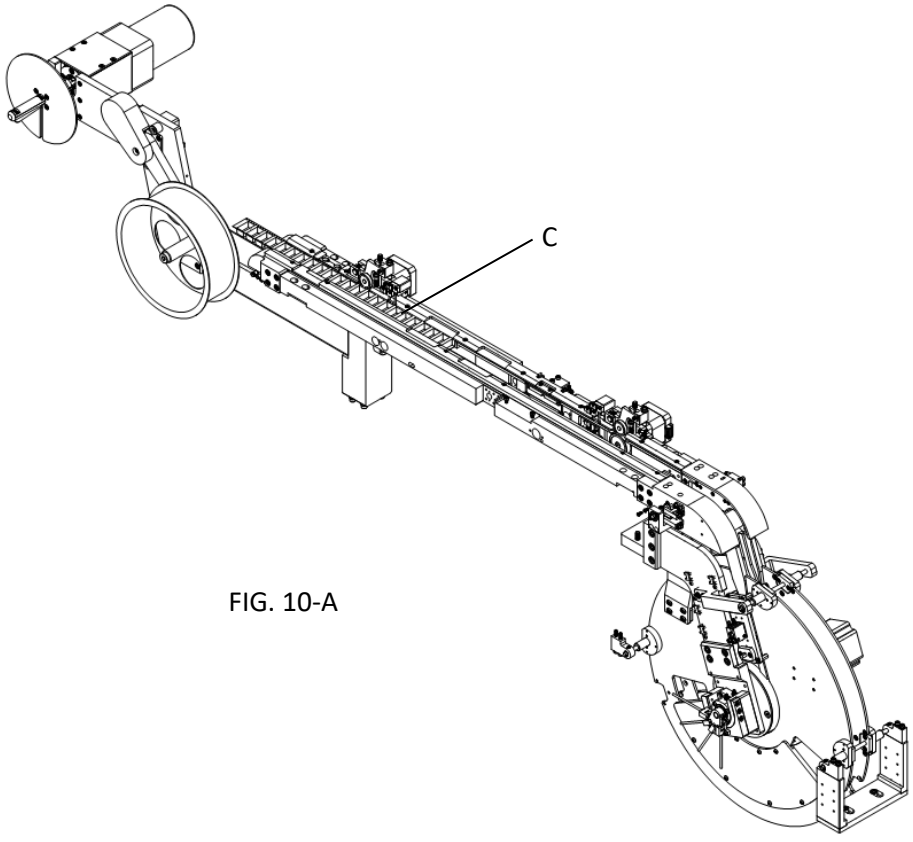


FIG. 10-A

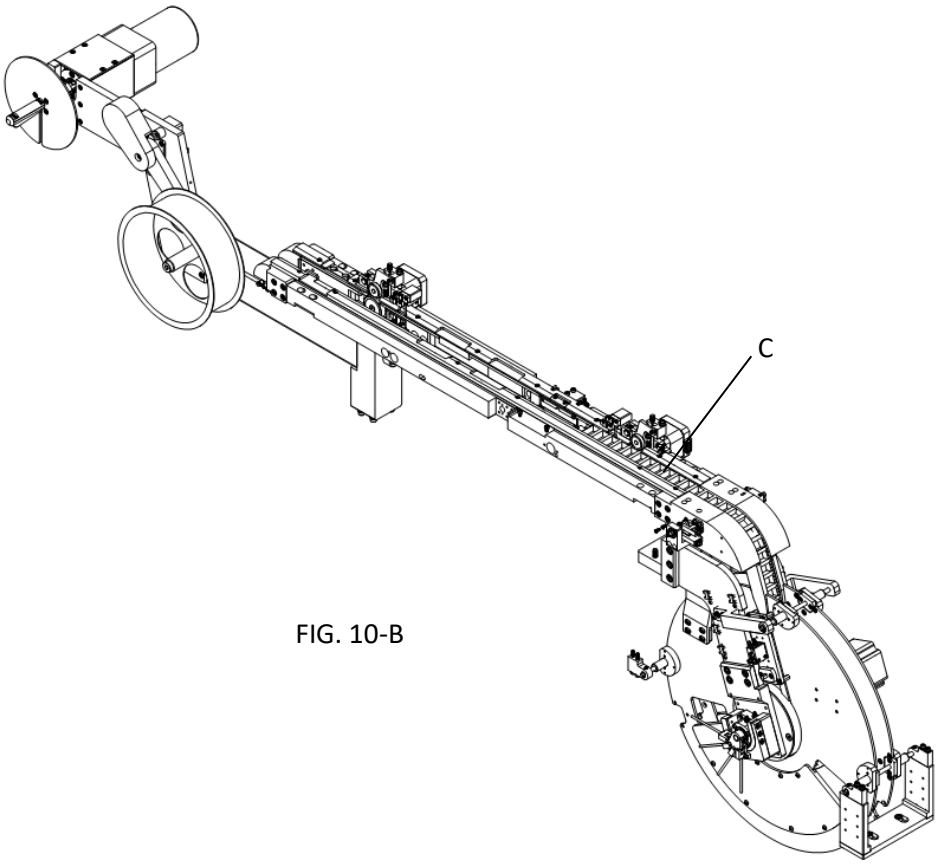


FIG. 10-B

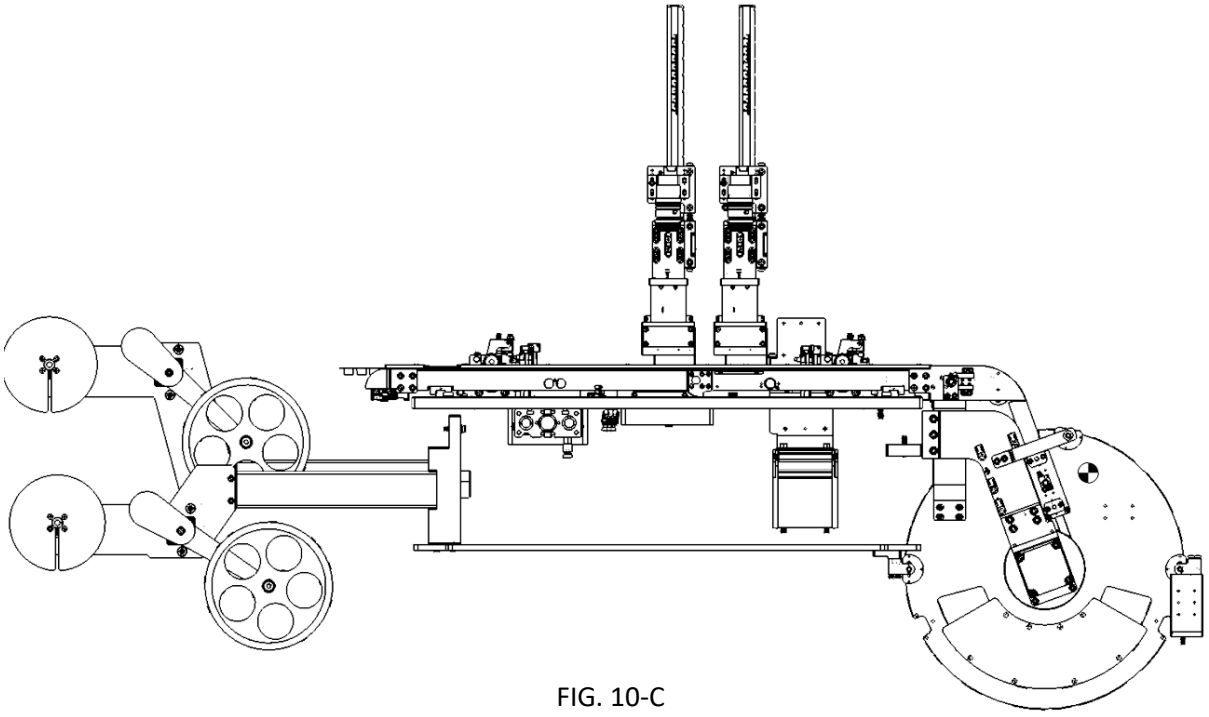


FIG. 10-C

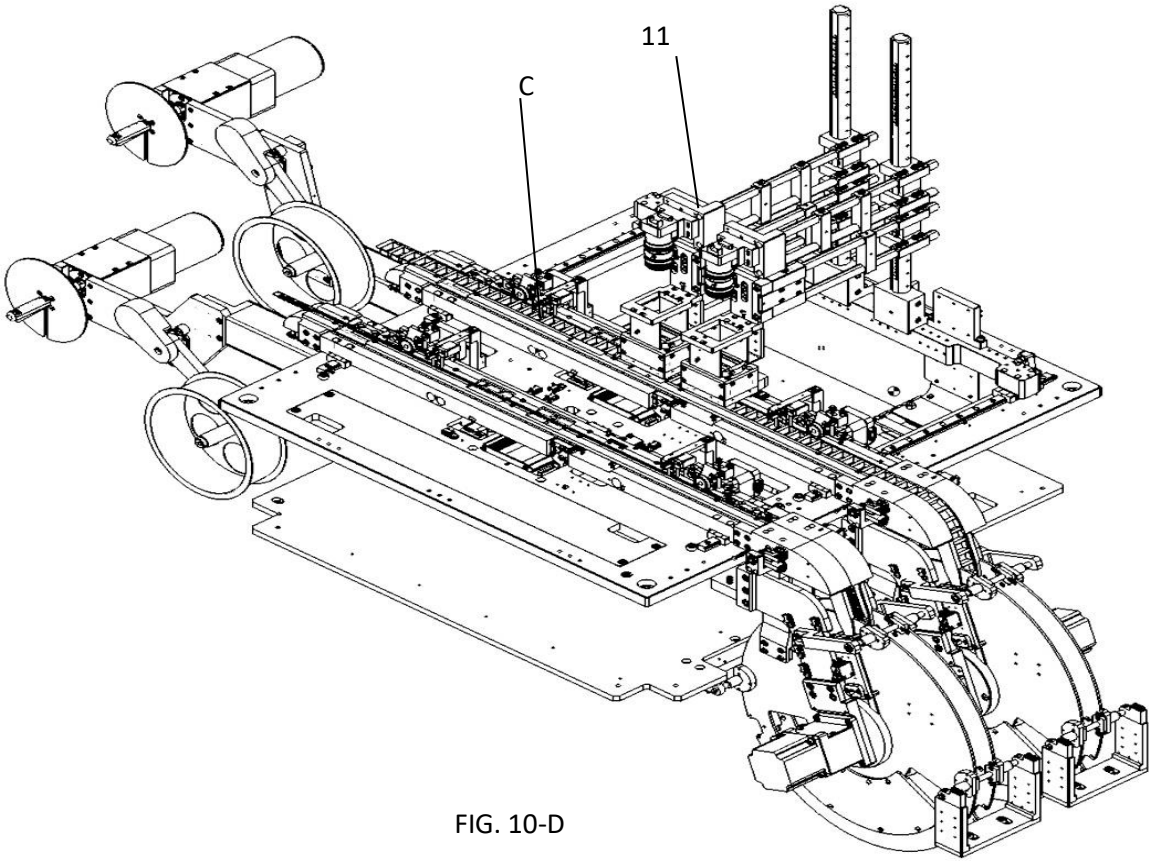


FIG. 10-D

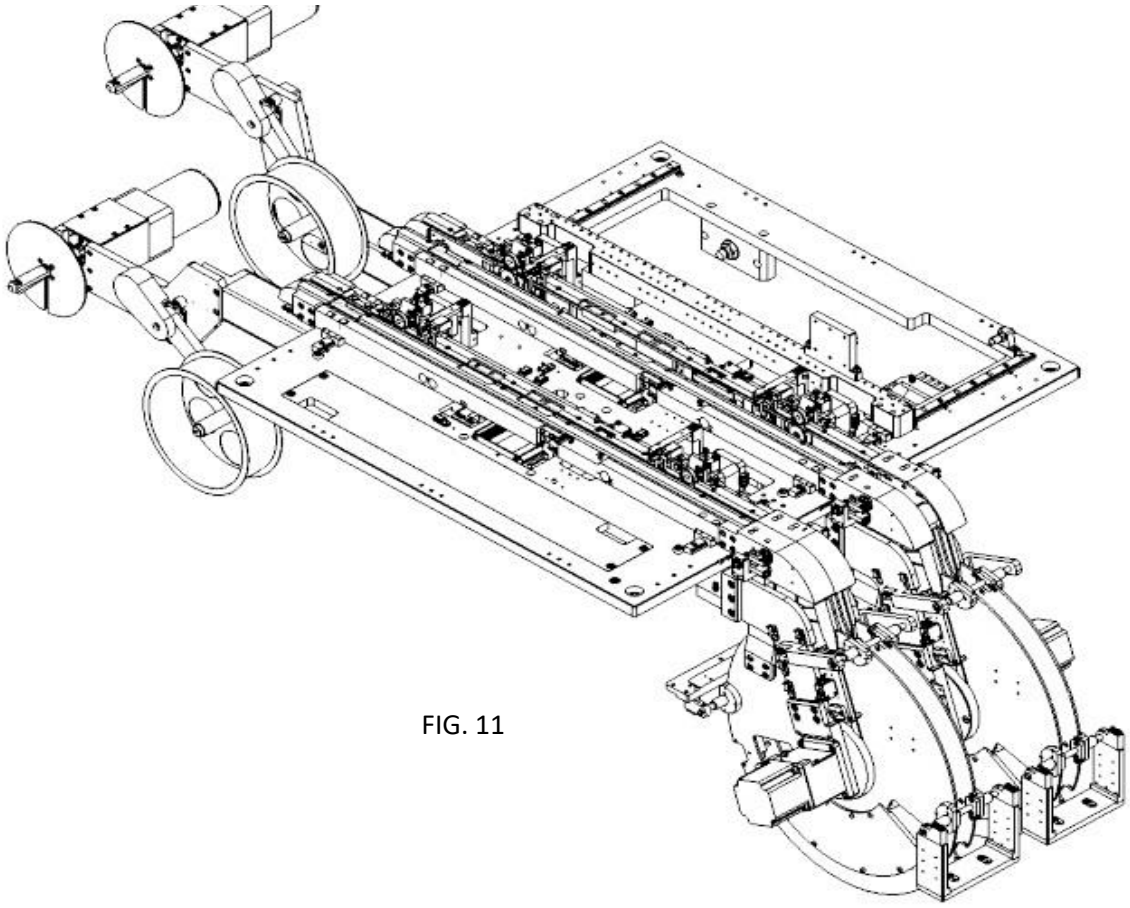


FIG. 11

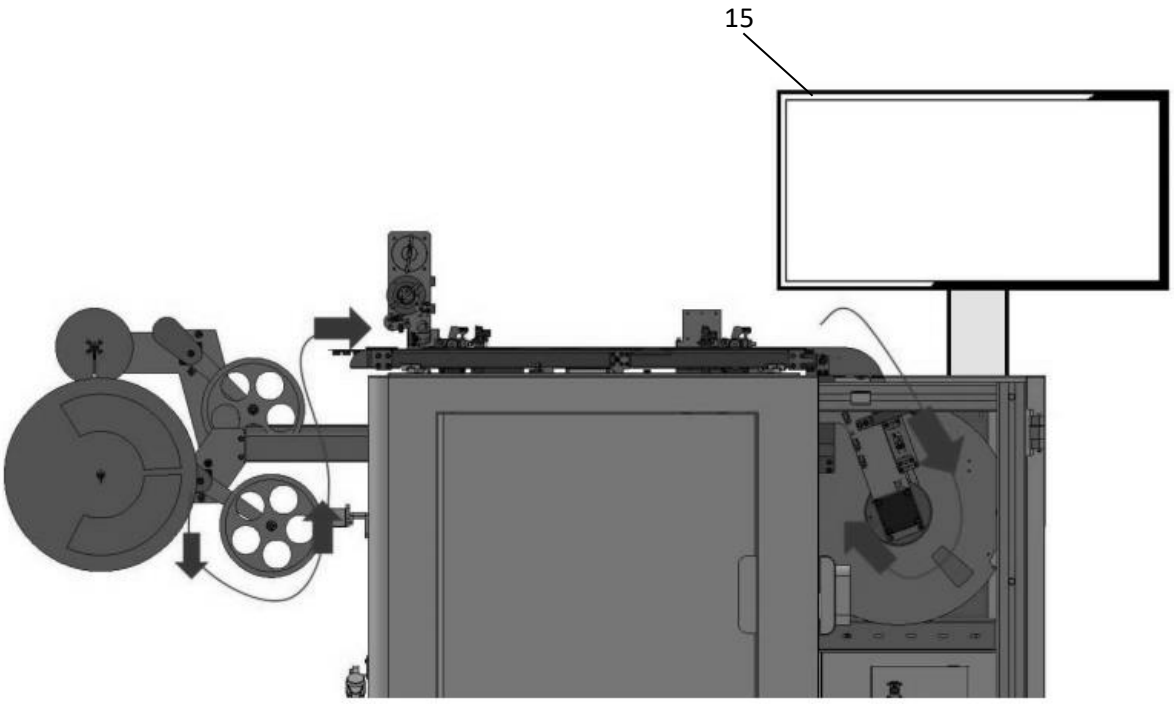

15

FIG. 12

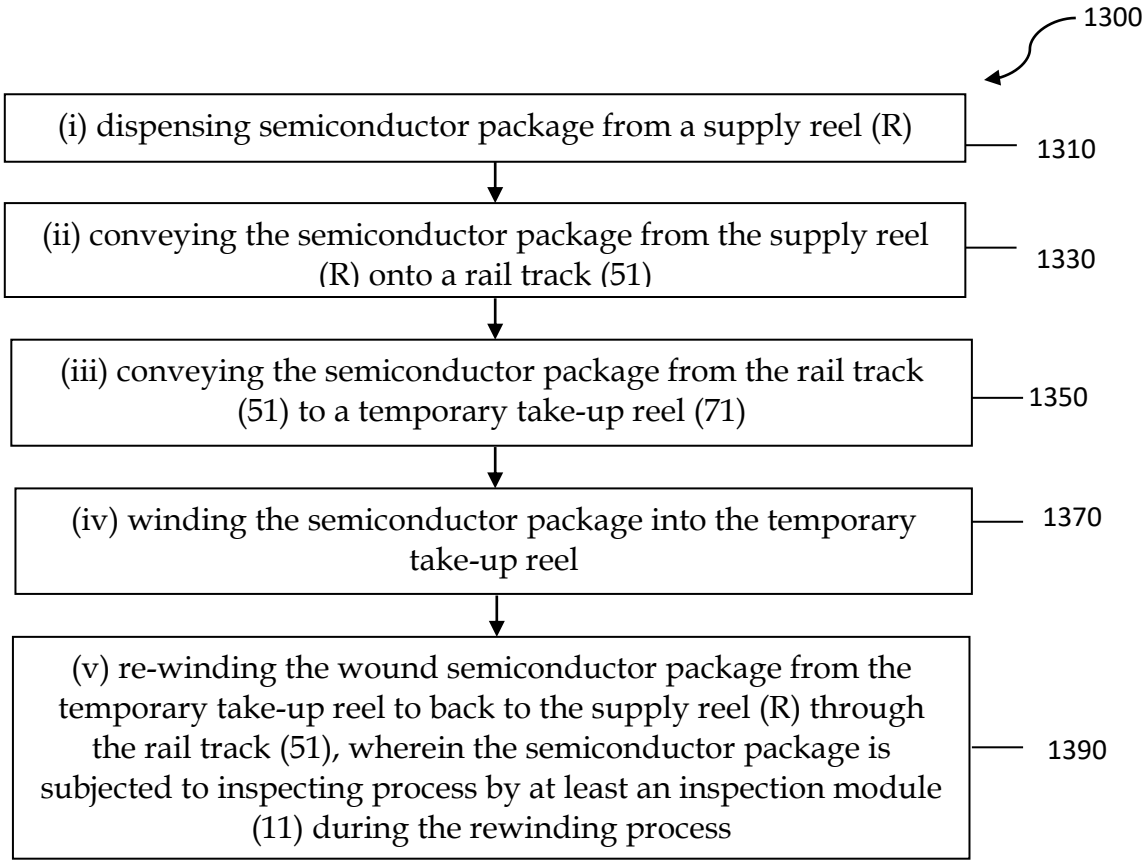

1300
(i) dispensing semiconductor package from a supply reel (R)
1310
(ii) conveying the semiconductor package from the supply reel (R) onto a rail track (51)
1330
(iii) conveying the semiconductor package from the rail track (51) to a temporary take-up reel (71)
1350
(iv) winding the semiconductor package into the temporary take-up reel
1370
(v) re-winding the wound semiconductor package from the temporary take-up reel to back to the supply reel (R) through the rail track (51), wherein the semiconductor package is subjected to inspecting process by at least an inspection module (11) during the rewinding process
1390

FIG. 13